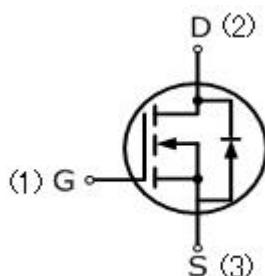


6N60(F,B,H)

6A mps,600 Volts N-CHANNEL MOSFET

FEATURE

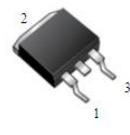
- 6A,600V, $R_{DS(ON)}=1.2\Omega$ @ $V_{GS}=10V/3A$
- Low gate charge
- Low C_{iss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



TO-220AB
6N60



ITO-220AB
6N60F



TO-263
6N60B



TO-262
6N60H

Absolute Maximum Ratings($T_c=25^\circ C$,unless otherwise noted)

Parameter	Symbol	6N60	UNIT
Drain-Source Voltage	V_{DSS}	600	V
Gate-Source Voltage	V_{GSS}	± 30	
Continuous Drain Current	I_D	6	A
Pulsed Drain Current(Note1)	I_{DM}	24	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	440	mJ
Avalanche Current(Note1)	I_{AR}	10.4	A
Repetitive Avalanche Energy (Note1)	E_{AR}	13	mJ
Reverse Diode dV/dt (Note 3)	dV/dt	5.0	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	260	°C
Mounting Torque	6-32 or M3 screw	10	lbf • in
		1.1	N • m

Thermal Characteristics

Parameter	Symbol	ITO-220	TO-220	TO-262 TO-263	Units
Maximum Junction-to-Case	R_{thJC}	1.25	1	1	°C/W
Maximum Power Dissipation	$T_c=25^\circ C$	P_D	100	125	W

Electrical Characteristics ($T_c=25^\circ\text{C}$, unless otherwise noted)						
Parameter	Symbol	Test Conditions	Mix	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=250\text{uA}$	600	—	—	V
Breakdown Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_J$	Reference to 25°C , $\text{I}_D=250\text{uA}$	—	0.53	—	$\text{V}/^\circ\text{C}$
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=600\text{V}, \text{V}_{\text{GS}}=0\text{V}$	—	—	1	uA
Gate-Body Leakage Current, Forward	I_{GSSF}	$\text{V}_{\text{GS}}=30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	—	—	10	uA
Gate-Body Leakage Current, Reverse	I_{GSSR}	$\text{V}_{\text{GS}}=-30\text{V}, \text{V}_{\text{DS}}=0\text{V}$	—	—	-10	uA
On Characteristics						
Gate-Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=250\text{uA}$	2	—	4	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}}=10\text{V}, \text{I}_D=3\text{A}$	—	—	1.2	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=25\text{V}, \text{V}_{\text{GS}}=0\text{V},$ $f=1.0\text{MHz}$	—	—	1123	pF
Output Capacitance	C_{oss}		—	—	112	pF
Reverse Transfer Capacitance	C_{rss}		—	—	21	pF
Switching Characteristics						
Turn-On Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}}=300\text{V}, \text{I}_D=6\text{A},$ $R_g=25\Omega$ (Note 4,5)	—	20	—	ns
Turn-On Rise Time	t_r		—	70	—	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$		—	40	—	ns
Turn-Off Fall Time	t_f		—	45	—	ns
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=480\text{V}, \text{I}_D=6\text{A},$ $\text{V}_{\text{GS}}=10\text{V}$ (Note 4,5)	—	22	—	nC
Gate-Source Charge	Q_{gs}		—	4.9	—	nC
Gate-Drain Charge	Q_{gd}		—	9.4	—	nC
Drain-Source Body Diode Characteristics and Maximum Ratings						
Continuous Diode Forward Current	I_S		—	—	6.0	A
Pulsed Diode Forward Current	I_{SM}		—	—	24	A
Diode Forward Voltage	V_{SD}	$I_S=6\text{A}, \text{V}_{\text{GS}}=0\text{V}$	—	—	1.4	V
Reverse Recovery Time	t_{rr}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_S=6\text{A},$ $dI_F/dt=100\text{A/us}$ (Note 4)	—	290	—	ns
Reverse Recovery Charge	Q_{rr}		—	2.35	—	uC

Notes

- Repetitive Rating:pulse width limited by maximum junction temperature.
- $\text{V}_{\text{DD}}=50\text{V}$, starting $L=24\text{mH}$, $R_g=25\Omega$, $I_{AS}=6\text{A}$, $T_J=25^\circ\text{C}$.
- $I_{SD} \leq I_D, dI/dt=200\text{A/us}$, $\text{V}_{\text{DD}} \leq \text{BV}_{\text{DSS}}$, starting $T_J=25^\circ\text{C}$.
- Pulse width $\leq 300\text{us}$; duty cycle $\leq 2\%$.
- Repetitive rating; pulse width limited by maximum junction temperature.